

## **Sensors and Materials**

### **Special Issue on Sensing and Data Analysis Technologies for Living Environment, Health Care, Production Management and Engineering/Science Education Applications**

With the rapid development of the Internet of Things (IoT), many IoT scenarios and applications are being proposed, and the number of sensors required for IoT scenarios and applications is rapidly increasing, resulting in rapid growth of the sensor chip market. Many new sensing and data analysis technologies, such as sensor fusion, multisensor, cloud-based computing, and big data analysis technologies, are being intensively researched and developed to meet the needs of more accurate and smart sensing.

The topics of this special issue will focus on sensing and data analysis technologies for living environment, health care, industrial production management, and engineering/science education applications.

Prospective authors are invited to submit their new manuscripts in line with the scope of this special issue.

Potential topics include but are not limited to the following:

- Sensors for pollution
- Early warning systems in the environment
- Production management technology using online sensing information.
- Big data analysis in sensing systems
- Data analysis/computing of smart sensors
- Mobile and wearable sensors
- Structural health monitoring
- Various sensor technologies and sensing systems
- Sensor fusion and sensorless applications
- Sensors and applications in the natural environment, including land, air, and water

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